

REMARKS/ARGUMENTS

Applicant would like to thank the Examiner for the careful consideration given the present application. The application has been carefully reviewed in light of the Office Action and it is respectfully submitted that the application is patentable over the art of record.

Claim 6 has been amended due to formal matters.

Claim 6 stands rejected under 35 U.S.C. 102(b) as being anticipated by Kakehi et al. (U.S. Patent No. 4,565,601). For at least the following reasons, the Examiner's rejection is respectfully traversed.

Kakehi does not disclose or teach "the top surface of the electrode has a top surface central area that is inside a boundary line that is distant inward by a prescribed length from an outer periphery of the substrate and in which the conductor is exposed and a ring-shaped top surface peripheral area that surrounds the top surface central area and in which the conductor is covered with an insulating coating" as recited in claim 6.

Kakehi discloses a lower electrode that includes an upper plate electrode 26 on which a substrate is mounted and an electrode cover 110 which protects the outer surface of the upper plate electrode 26 where the substrate is not mounted (col. 4, lines 31–66). In Kakehi, the surface of the upper plate electrode 26 where the substrate is mounted is coated with an insulating film 60 (col. 3, lines 61–63, and col. 4, lines 58–63). Kakehi also discloses a tool 120 for pressing the substrate to the lower electrode 20 by pressing the periphery of the substrate (col. 8, line 49–57).

Since the entire Kakehi upper plate electrode is *coated* with an insulating film, Kakehi does not teach a top surface central area in which the conductor is *exposed* and a ring-shaped top

surface peripheral in which the conductor is *covered* with an insulating covering. Therefore, Kakehi does not disclose or suggest all the elements of the claimed invention.

Further with regards to claim 6, Kakehi does not disclose or teach “mounting the substrate on the top surface of the electrode in such a manner that a central portion and a peripheral portion of the insulating layer of the substrate are in contact with the top surface central area and the insulating coating in the top surface peripheral area, respectively” as recited in claim 6.

As mentioned previously, the entire surface of the Kakehi upper plate electrode 26 is coated with an insulating film 60 (col. 3, lines 61–63, and col. 4, lines 58–63). In Kakehi, the under surface of the substrate 50 is placed on the lower electrode 20 by mating the substrate surface to the insulating film 60 (col. 5, lines 34–38).

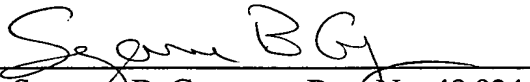
Since the *entire substrate surface* is mated to the *insulating film* of the Kakehi upper plate electrode, Kakehi does not teach that a central portion of the substrate is in contact with the top surface central area of the electrode and a peripheral portion of the substrate is in contact with the top surface peripheral area of the electrode. Thus, Kakehi does not disclose or teach all elements of the claimed invention.

In light of the foregoing, it is respectfully submitted that the present application is in a condition for allowance and notice to that effect is hereby requested. If it is determined that the application is not in a condition for allowance, the Examiner is invited to initiate a telephone interview with the undersigned attorney to expedite prosecution of the present application.

Appln. No. 10/621,497
Amdt. Dated August 31, 2005
Reply to Office Action of June 9, 2005

If there are any additional fees resulting from this communication, please charge same
to our Deposit Account No. 16-0820, our Order No. 35908.

Respectfully submitted,
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